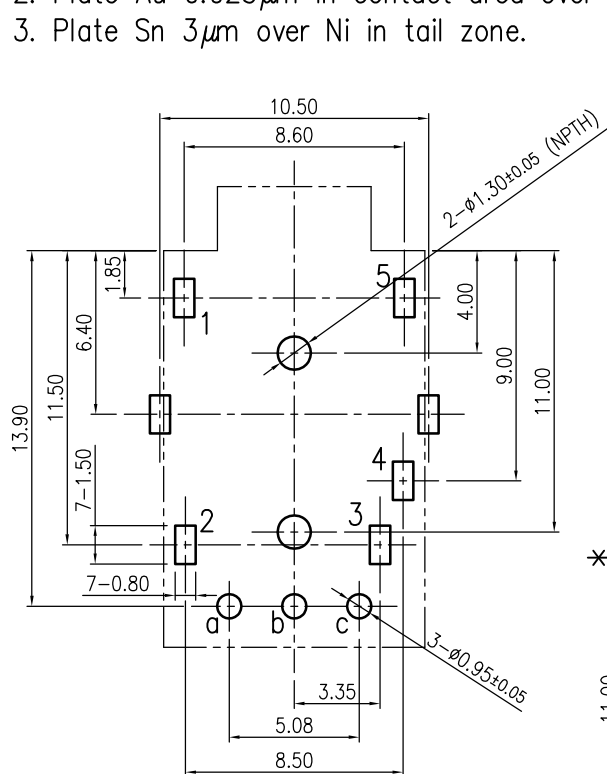
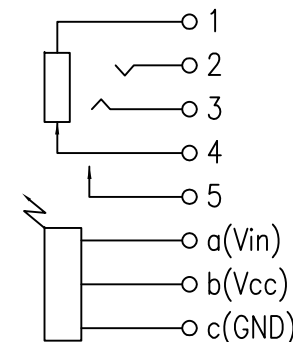
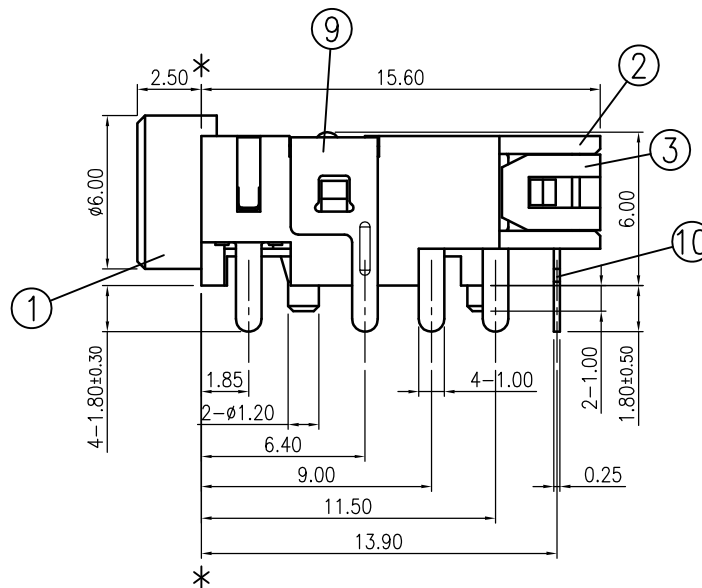
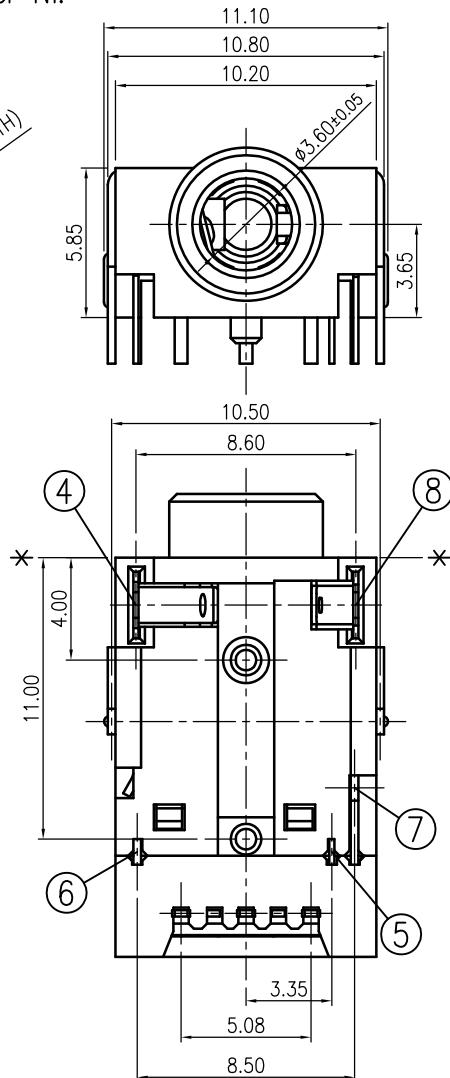
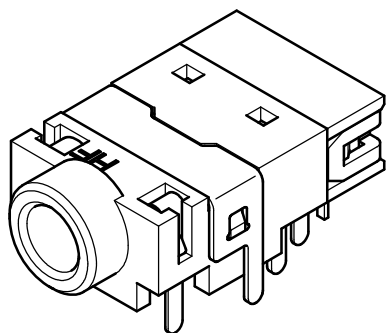


Note:
 Plating of EARTH SPRING-A, RING SPRING, TIP SPRING,
 EARTH SPRING-B (LTR.4~7) is as follows:
 1. Under-plate Ni 2 μ m all over base material.
 2. Plate Au 0.025 μ m in contact area over Ni.
 3. Plate Sn 3 μ m over Ni in tail zone.



PCB Layout Dimension (Tolerance: ± 0.10)
 (Recommend min. Dimension)(Bottom View)



Circuit diagram

10	LIGHT TRANSMITTING UNIT(a~c)	1		
9	SHIELD	1	Ferro alloy t=0.30	MFCu5 μ m-Ni3 μ m
8	MAKE SPRING(5)	1	Copper alloy t=0.20	MBCu2 μ m-Sn3 μ m
7	EARTH SPRING-B(4)	1	Copper alloy t=0.30	See note
6	TIP SPRING(2)	1	Copper alloy t=0.30	See note
5	RING SPRING(3)	1	Copper alloy t=0.20	See note
4	EARTH SPRING-A(1)	1	Copper alloy t=0.20	See note
3	COVER	1	High temperature thermoplastic(HF) UL 94V-0	Black
2	BASE	1	High temperature thermoplastic(HF) UL 94V-0	Black
1	HOUSING	1	High temperature thermoplastic(HF) UL 94V-0	Black

LTR	PART NAME	Q'TY	MATERIAL	REMARK
120~315	± 0.5	DWN	黄健璋	DATE 2012.10.04
30~120	± 0.35	DSND	黄健璋	DATE 2012.04.24
6~30	± 0.22	CHKD	郭素玲	DATE 2012.10.04
BELOW 6	± 0.16	APVD	郭远峰	DATE 2012.10.04
DIMENSION	TOLERANCE	KUNMING ELECTRONICS CO.,LTD.		DWN.NO. 1/1
				A-35004B00BC0Q1 001

SCALE 3.2/1
 PROJECTION
 UNIT: mm

NAME MINIATURE JACK with optical
 CAT. NO. KM35004B00BC0Q1
 DWN.NO. 1/1
 A-35004B00BC0Q1 001